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In re Patent Application of

TAKAFUJI et al Atty. Ref.: 1035-501

Serial No. 10/802,735 Group: 2811

Filed: March 18, 2004 Examiner:

For: SEMICONDUCTOR DEVICE AND METHOD OF

MANUFACTURING THE SAME

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

Sir:

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Further to applicants' Information Disclosure Statement of June 7, 2004, applicants herewith submit a <u>corrected</u> Form PTO-1449 (i.e., the page numbers of the Tong et al reference and the date of the Vandooren et al reference has been corrected).

Respectfully submitted, NIXON & VANDERHYE P.C.

June 25, 2004

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							Form PTO-FB-	A820 (Also	PTO-1449)	